2SA1700

Rev.E May.-2016

蓝箭电子 BLUE ROCKET ELECTRONICS

DATA SHEET

/ Descriptions

WR0585 ṂṂ Ł SQS ÆṀ ч s ǁ ᒣ Silicon PNP transistor in a TO-252 Plastic Package.

/ Features

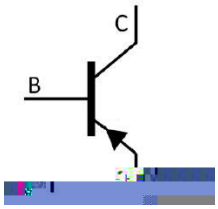
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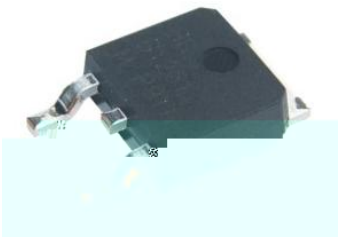
High breakdown voltage, adoption of MBIT process excellent h_{FE} linearity

[redacted]

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High voltage driver applications.



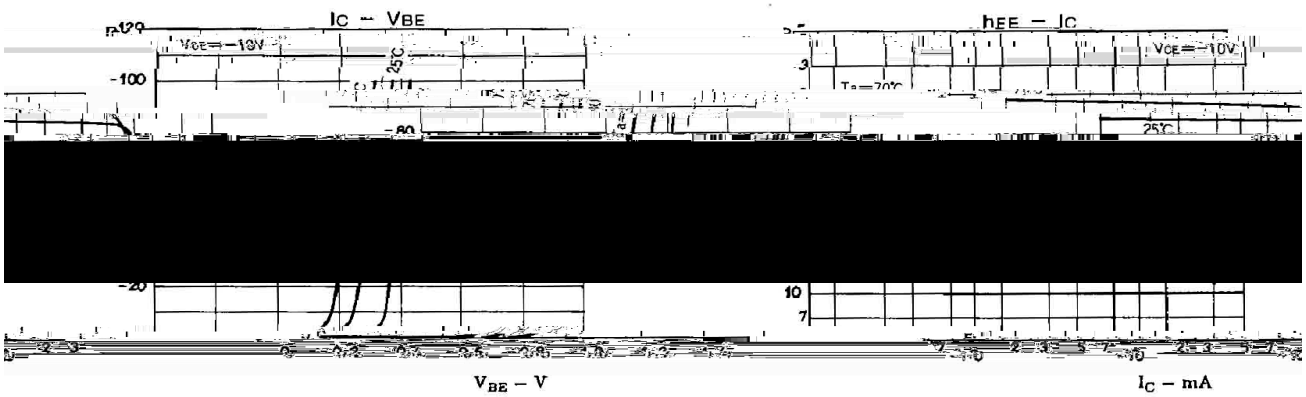


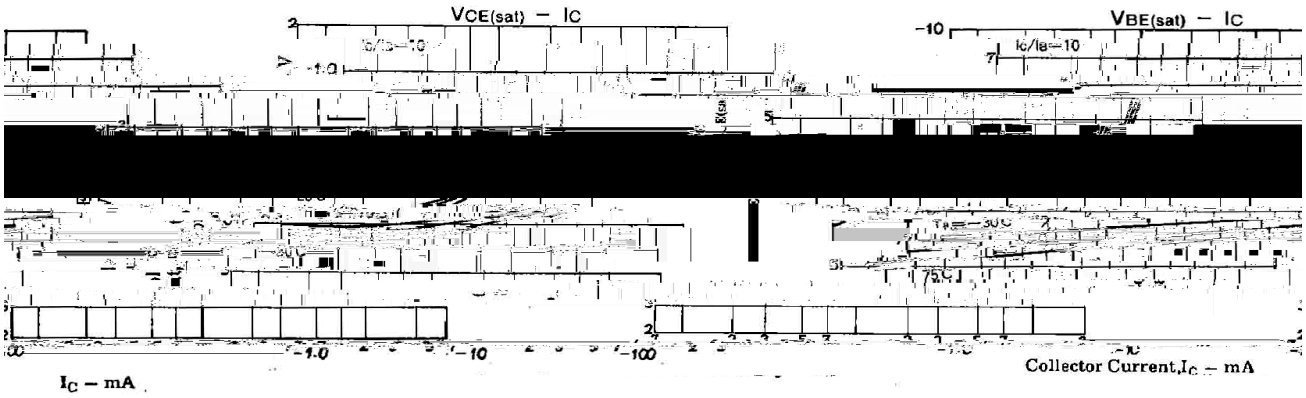
PIN1 χ Base PIN 2,4 χ Collector PIN 3 χ Emitter

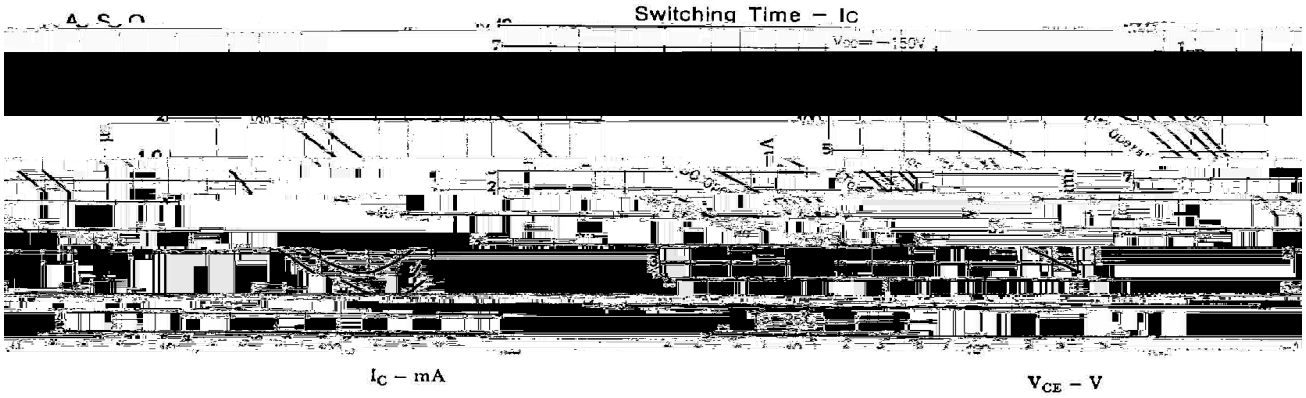
/ h_{FE} Classifications & Marking

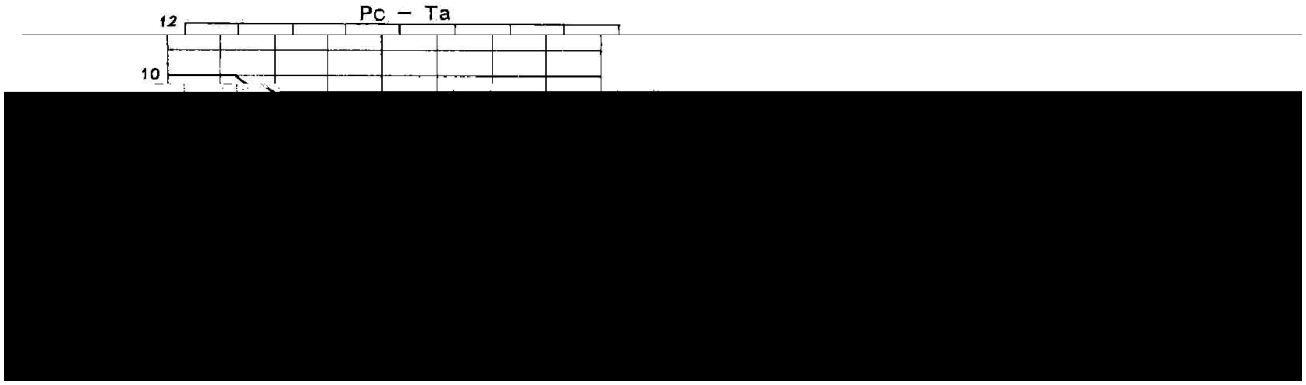
v ˝Ω Parameter	ϒ N Symbol	˝Ω Ө Rating	D Ч Unit
Collector to Base Voltage	V_{CBO}	-400	V

/ Electrical Characteristic Curve

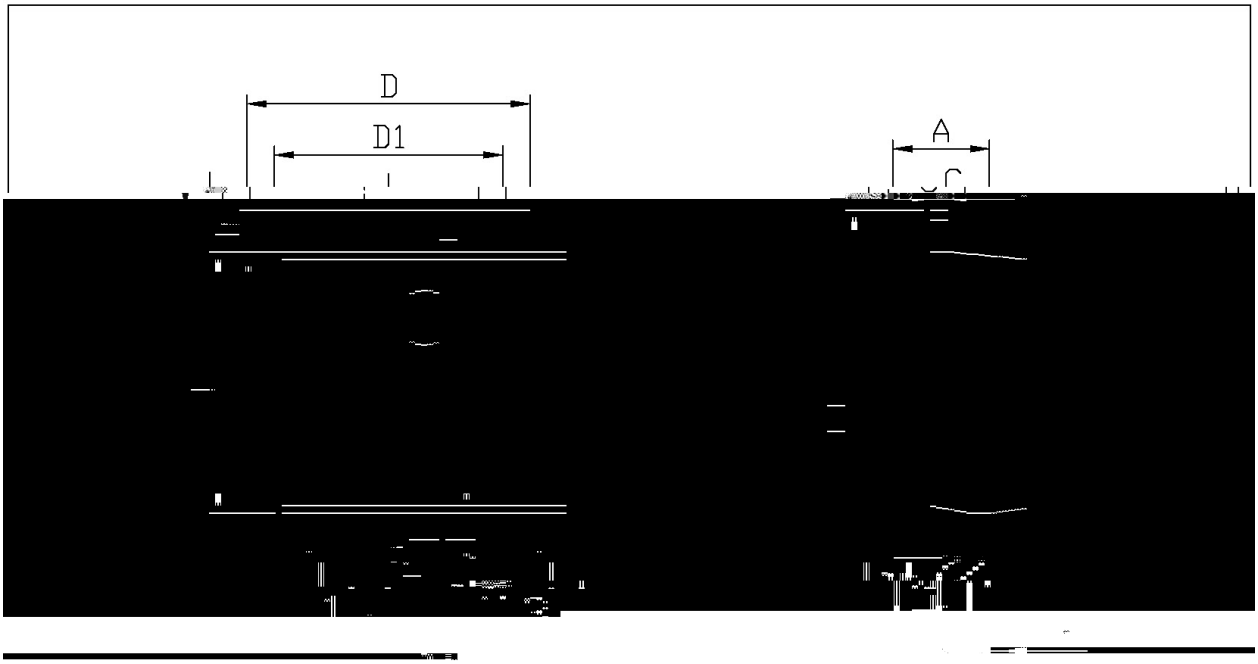






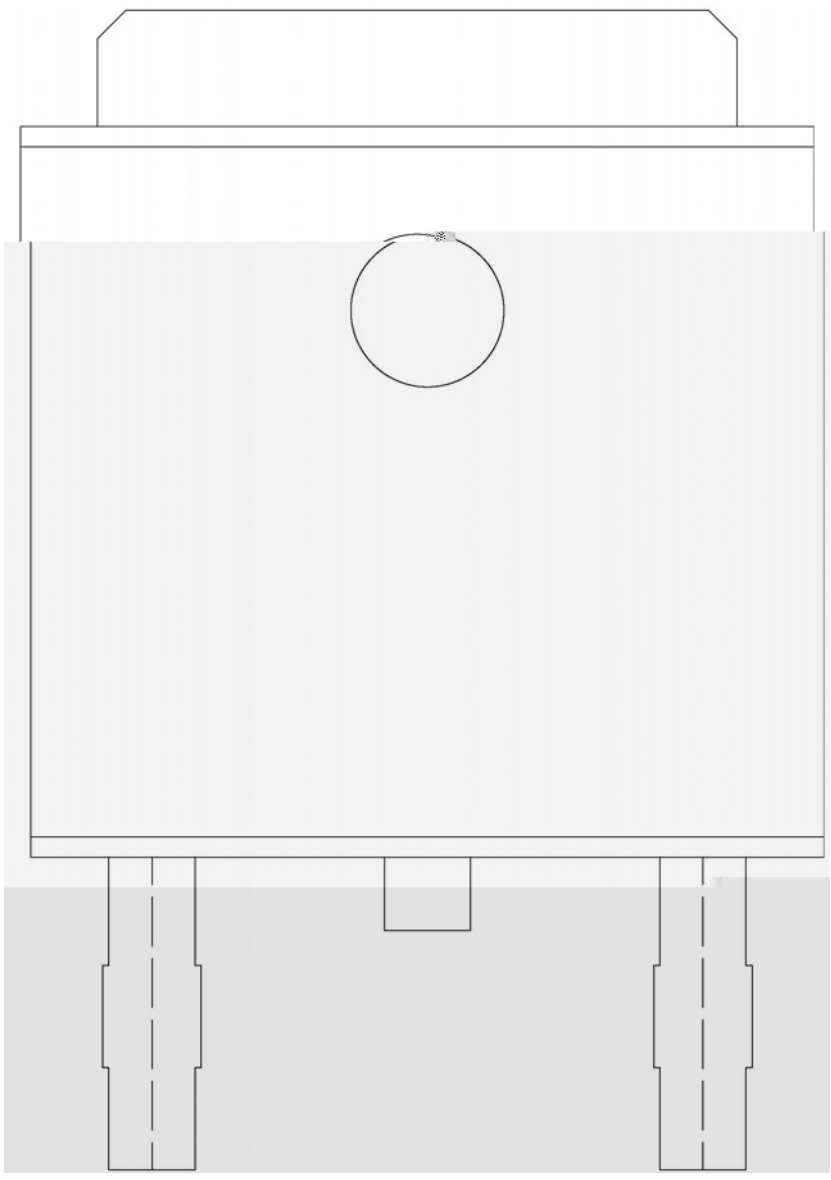


/ Package Dimensions



	4.75				
	0.95	b1	0.45	0.55	L1	9.45
25	1.75	C	0.45	0.55	L2	1.
.60	0.90	D	6.45	6.75	L3	0
0.00	0.10	D1	5.10	5.50	K	

/ Marking Instructions



ب ˝ χ

BR χ ㎗ ʇ ᴻ Ꮒ

A1700 χ ㎗ ʒ ᴺ Ꮒ

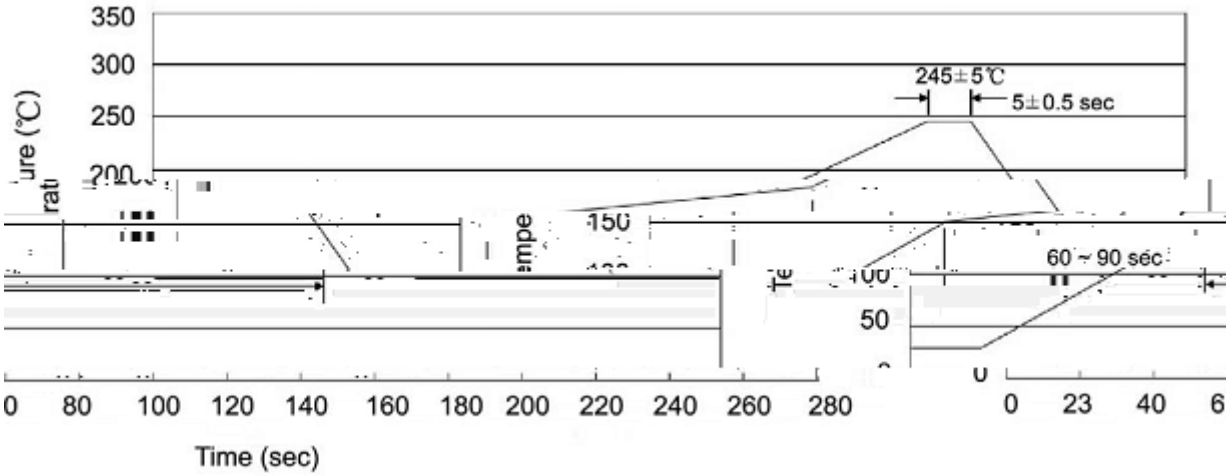
D: ㎗ h_{FE} ˂ ⁶ Ꮒ

---- χ ㎗ ꟷ ꞙ ῄ ᴺ Ꮒ ı ꬶ ꟷ ꞙ ῄ ᴺ ψ ק

Note:

BR: A13( )Tj22ɖ/TT7ψ̀LOFÖ Company

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



ب ˝ χ

1 Ĺ ♬ □ ỷ 25 Ḱ 150 ɬ ı ̀H ڑ 60 Ḱ 90sec;

2 Š Ö □ ỷ 245 ° 5 ɬ ı ̀H ڑ ̀Y ʌ ʁ 5 ° 0.5sec;

3 ì ˙ ϒ ˛ ɔ ֍ ỷ ʁ 2 Ḱ 10 ɬ /sec.

Note:

1.Preheating:25~150 ɬ , Time:60~90sec.

2.Peak Temp.:245 ° 5 ɬ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɬ /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 260 ° 5 ɬ	̀H ڑ χ 10 ° 1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

ɔ ` ϒ Ł / REEL

Package Type	Units	Dimension	(unit mm^3)